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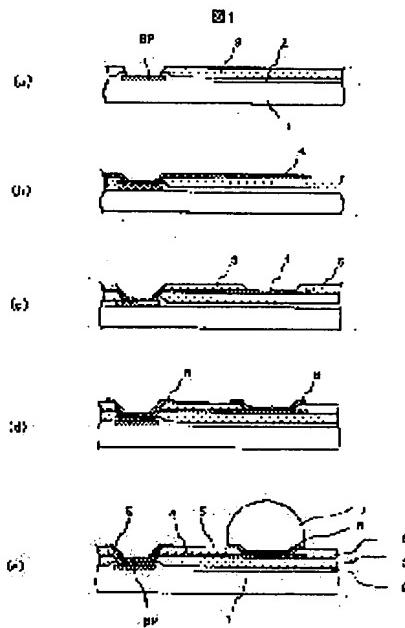
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 HATTORI KOJI**(54) PATTERN FORMING METHOD AND MANUFACTURING METHOD FOR SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE****(57)Abstract:**

**PROBLEM TO BE SOLVED:** To reduce the mask cost and to increase the productivity of many kinds of high-performance semiconductor devices in small quantities according to customer's usages.

**SOLUTION:** A semiconductor integrated circuit device is manufactured by using an inexpensive exposing device which uses a mercury lamp as its light source and a photomask which uses organic photosensitive resin as a substantial shading material for a process of forming a bonding pad and rearranged wires.

**LEGAL STATUS**

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